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(19) **United States**(12) **Patent Application Publication**  
**Heydari**(10) **Pub. No.: US 2022/0361375 A1**(43) **Pub. Date: Nov. 10, 2022**(54) **SERVER UNIT WITH BUILT-IN FLOW DISTRIBUTION**(52) **U.S. Cl.**CPC ..... *H05K 7/20781* (2013.01); *H05K 7/20254* (2013.01); *H05K 7/20272* (2013.01); *H05K 7/20281* (2013.01)(71) Applicant: **Nvidia Corporation**, Santa Clara, CA (US)(72) Inventor: **Ali Heydari**, Albany, CA (US)

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**ABSTRACT**(21) Appl. No.: **17/307,762**(22) Filed: **May 4, 2021****Publication Classification**(51) **Int. Cl.*****H05K 7/20***

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Configurations for cooling systems are disclosed. In at least one embodiment, one or more distribution manifolds are formed within at least one panel of a server unit housing to receive a liquid and direct the liquid to one or more outlets, the one or more outlets to couple to one or more cold plates.

